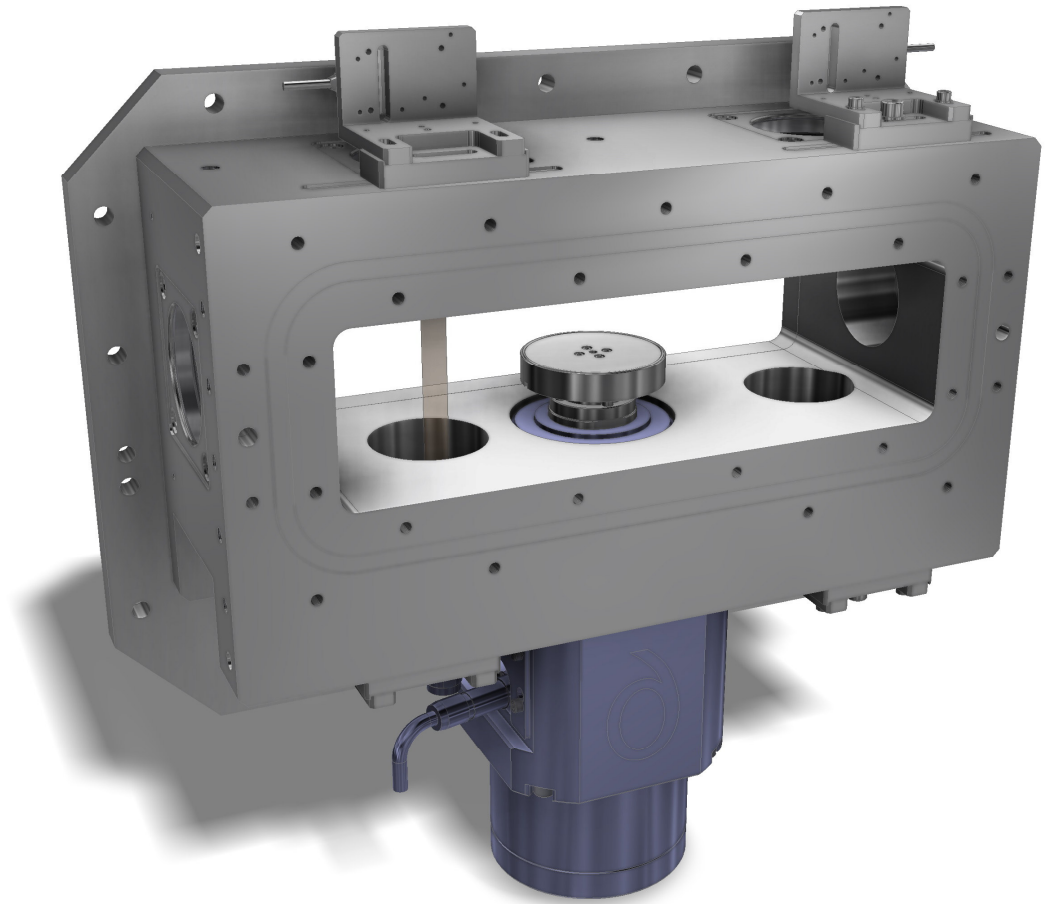


# WAM300

## Wafer Alignment Module for vacuum environment



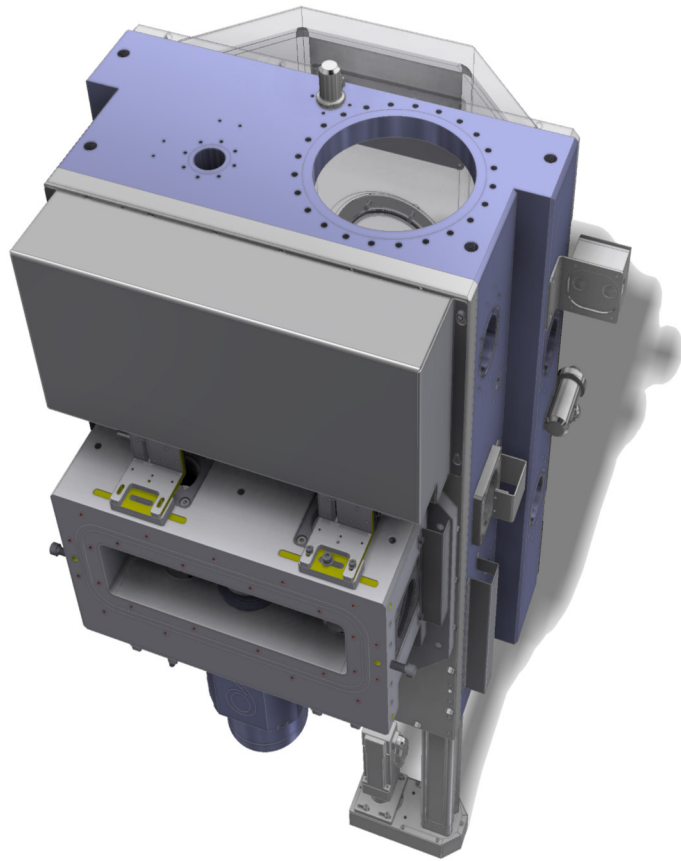
### ADVANTAGES:

- ✓ **INTEGRABLE**  
easy integration into cluster systems
- ✓ **FLEXIBILITY**  
different substrate sizes and geometries
- ✓ **PRODUCTIVITY**  
fast alignment
- ✓ **PRECISION**  
precise Adenso DDU direct drive unit
- ✓ **COMPLEXITY**  
save invest and operating costs with Adenso.Solutions

# WAM300

## Wafer Alignment Module for vacuum environment

**Adenso**  
solutions you need



### Advantages

- ✓ higher productivity
- ✓ more cleanroom space
- ✓ optimized costs
- ✓ greater flexibility
- ✓ progressive products
- ✓ new markets
- ✓ ...

This picture shows the WAM300 integrated to a FOUP VAC.LOADPORT for direct wafer handling from FOUP to process inside a vacuum cluster system.

### SPECIFICATION

#### Substrates

- Wafer 300mm
- Wafer 200mm
- all kind of substrate geometry can be detected

#### PAYLOAD

Standard: up to 1kg

#### CLEAN ROOM

Clean room suitability  
up to ISO class 3 / US FED class 1

#### INTERFACES

Ethernet

## The blue Adenso.Solution

Smart with a small footprint and a lot of advantages for Adenso.Clients  
For alignment of 300mm wafer inside cluster systems directly and without (!) atmospheric handling robots.

The WAM300 is excellent for combination with Adenso WHR Wafer Handling Robot—via interface the robot gets automatically the correction data from the Wafer Alignment Module.

### Footprint

Saves cleanroom floor space because of direct integration into vacuum environment.

### Costs

Saves investment and operating costs for unnecessary tools.

Discover new possibilities to build up new business segments!

[www.waferhandling.solutions](http://www.waferhandling.solutions)

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